

SPECIFICATION AND PERFORMANCE

Series	112J-TXAR-R01	File	112J-TXAR-R01_spec_2	Date	2024/05/07
---------------	----------------------	-------------	-----------------------------	-------------	-------------------

Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of below

Part Name	Description
112J-TDAR-R01	Micro SD Socket, Push-Push Type, Reel, H=1.85mm, w/switch, (w/Logo), 10u" Gold Plated
112J-TAAR-R01	Micro SD Socket, Push-Push Type, Reel, H=1.85mm, w/switch, (w/Logo), Gold Flash

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS

NO.	PART NAME	DESCRIPTION
1	Housing	LCP+35%GF, Color: Black
2	Slider	LCP+35%GF, Color: Black
3	Contact	Phosphor Bronze Alloy (C5210) Contact area: Gold flash or Gold 10 u" Solder area: Gold flash All under-plated Ductile Nickel 50 u"(Min.)
4	Shell	Stainless SUS304, Gold Flash on Solder Area under 12u" Nickel (Min.)
5	Drag Link	Stainless SUS304 or SUS130M
6	Spring	Piano wire

RATING

Rated Current	0.5A (Max.)/(1PIN)
Rated Voltage	100V AC/DC
Operating Temperature	-40°C to +90°C
Storage Temperature	-40°C to +90°C
Durability	10,000 Cycles

ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	Initial:	Solder connectors on PCB and mate them



	50 mΩ (Max)	together, measure by applying closed circuit current of 10mA maximum at open circuit voltage of 20mV (max). (JIS C5402 5.4)
Insulation Resistance	Initial: 1000 MΩ(Min).	Apply 500V DC between adjacent contacts, or contact and ground. (MIL-STD-202 METHOD 302)
Dielectric Withstanding Voltage	No breakdown	Mate connectors; apply 500V AC (rms.) between two adjacent for 1minute. (Trip current:1mA) (MIL-STD-202 METHOD 301)

MECHANICAL

Item	Requirement	Test Condition
Contact Retention Force	2.5N per pin (Min.)	Place a connector on the push-pull machine, then apply a force on a contact head and push the contact to the opposite direction of the contact insertion at the speed of 25 ± 3mm/min. (EIA364-29)
Durability	Finish 1.Contact Resistance: 80mΩ (Max) 2.No Damage	Solder connectors on PCB, then place them on the pull-push machine, and repeat mating and un-mating 10,000cycles repeatedly at a rate of 400~600 cycles/hour. (EIA364-09)
Vibration	Finish 1. No electrical discontinuity more than 0.1μs. 2 .No Damage 3. Contact Resistance: 80mΩ (Max)	Mate dummy card and subject to the following vibration conditions, for a period of 30 minutes in each of 3 mutually perpendicular axis, passing DC 1 mA during the test. Amplitude: 1.52 mm P-P or 19.6 m/s ² Frequency: 10-55-10Hz Shall be traversed in 1minute. (MIL-STD-202 METHOD 201)
Shock	Finish 1. No electrical discontinuity more than 0.1μs. 2 .No Damage 3. Contact Resistance: 80mΩ (Max)	Solder connectors on PCB and mate them together, subject to he following shock conditions, 3 shocks shall be period along 3 mutually perpendicular axis, passing DC 1mA current during the test. 1 axis, plus-minus direction, core 3times.(total:18times) 490m/s ² (MIL-STD-202 METHOD 213)
Card Insertion / Eject Force	9.8N(Max)	Push the card at the speed rate 25 ± 3 mm/minute.
Card Release Force	2N+/-1N	From the state of the card lock, Pull the card at the speed rate 25 ± 3 mm/minute.
Push in strength	No Damage	The card inserted in positive and the opposite



		direction and the load of 19.6N is added
--	--	--

ENVIRONMENTAL

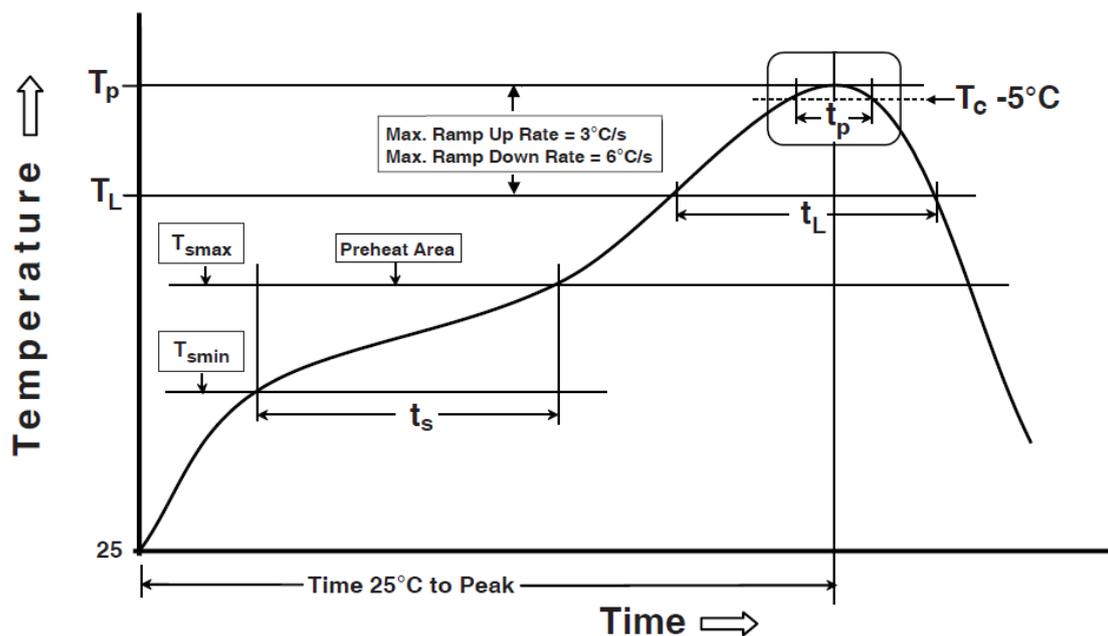
Item	Requirement	Test Condition															
Humidity	Finish 1. Contact Resistance: 80mΩ (Max) 2. Insulation Resistance: 100MΩ (Min)	Humidity storage at +40°C with 90~95% RH for 96 hours. Upon completion of the exposure period, the test specimens shall be conditions for 1 of 2 hrs, then 10 mating cycles while. (EIA364-31)															
Temperature Cycle	Finish 1. Contact Resistance: 80mΩ (Max) 2. Insulation Resistance: 100MΩ (Min)	<table style="width: 100%; border-collapse: collapse;"> <tr> <td style="text-align: left;">Stage</td> <td style="text-align: left;">Temp</td> <td style="text-align: left;">Time</td> </tr> <tr> <td>t1</td> <td>-55°C</td> <td>30 min</td> </tr> <tr> <td>t2</td> <td>-55~+90°C</td> <td>3 min</td> </tr> <tr> <td>t3</td> <td>+90°C</td> <td>30 min</td> </tr> <tr> <td>t4</td> <td>+90~-55°C</td> <td>3 min</td> </tr> </table> Test time: 6 cycles (JIS C0025)	Stage	Temp	Time	t1	-55°C	30 min	t2	-55~+90°C	3 min	t3	+90°C	30 min	t4	+90~-55°C	3 min
Stage	Temp	Time															
t1	-55°C	30 min															
t2	-55~+90°C	3 min															
t3	+90°C	30 min															
t4	+90~-55°C	3 min															
Heat Resistance	Finish 1. Contact Resistance: 80mΩ (Max) 2. Insulation Resistance: 100MΩ (Min)	Solder connectors on PCB and mate them together, expose to 90 ± 20°C for 96hrs. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2hrs, after which the specified measurements shall be performed. (MIL-STD-202 METHOD 108)															
Cold Resistance	Finish 1. Contact Resistance: 80mΩ (Max) 2. Insulation Resistance: 100MΩ (Min)	Solder connectors on PCB and mate them together, expose to -55 ± 30°C for 96hrs. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2hrs, after which the specified measurements shall be performed. (EIA364-59)															
Salt Spray	Finish 1. Contact Resistance: 80mΩ (Max) 2. No Damage	5 ± 1% salt solutions, at 35 ± 2°C duration 48 hours. Connectors detached (MIL-STD-1344)															

SOLDER ABILITY

Item	Requirement	Test Condition
Solder ability	95%of immersed area must show no voids, pin holes.	Dip solder tails into the molten solder(held at 230±5°C) up to 0.5mm from the tip of tails for 3±0.5 seconds. (MIL-STD-202 METHOD 208)
Resistance to soldering heat	No melting, cracks or functional damage allowed	All connectors designed for PCB soldering within this specification must be able to

withstand the heat from solder oven according to the graph below. The cycle should be repeated twice.
 (MIL-STD-202 METHOD 210)

Reflow Profile



Preheating temperature: 150 ~ 200°C, 60~120 seconds
 Liquidus temperature (TL): 217°C, 60~150 seconds
 Peak temperature: 260°C
 Time within 5 °C of peak temperature (Tc): 255°C, 30seconds